

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A material comprising:
a dielectric paste for forming a spacer layer, the dielectric paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate and d-dihydrocarvyl acetate as a solvent.
2. (Currently Amended) ~~The material A dielectric paste adapted for forming a spacer layer~~ in accordance with Claim 1, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000
3. (Currently Amended) ~~The material A dielectric paste adapted for forming a spacer layer~~ in accordance with Claim 1, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.
4. (Currently Amended) ~~The material A dielectric paste adapted for forming a spacer layer~~ in accordance with Claim 2, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.